

General Description

The Sanrise SRT10N043H is a low voltage power MOSFET, fabricated using advanced split gate trench technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and synchronous rectification.

The SRT10N043H break down voltage is 100V and it has a high rugged avalanche characteristics. The SRT10N043H is available in PDFN5*6 and TO-220C and TO-263-2 packages.

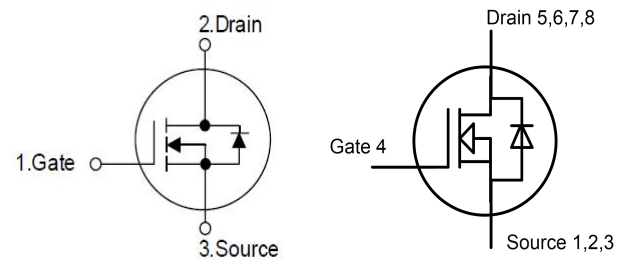
Features

- Ultra Low
 $R_{DS(ON_TYP)} = 3.7m\Omega$, PDFN5*6 @ $V_{GS} = 10V$.
 $R_{DS(ON_TYP)} = 4.1m\Omega$, TO-220C @ $V_{GS} = 10V$.
 $R_{DS(ON_TYP)} = 3.9m\Omega$, TO-263-2 @ $V_{GS} = 10V$.
- Ultra Low Gate Charge, $Q_g=57nC$ typ.
- Fast switching capability
- Robust design with better EAS performance

Application

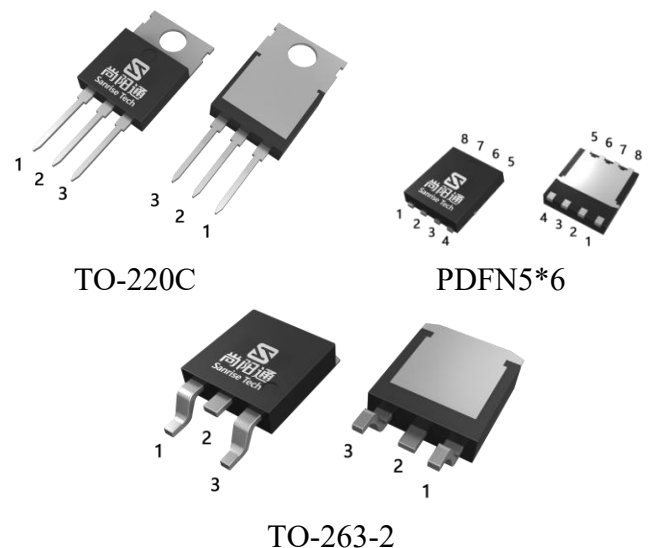
- Server/Telecom
- High Power Supply
- E-Tools
- BMS

Symbol

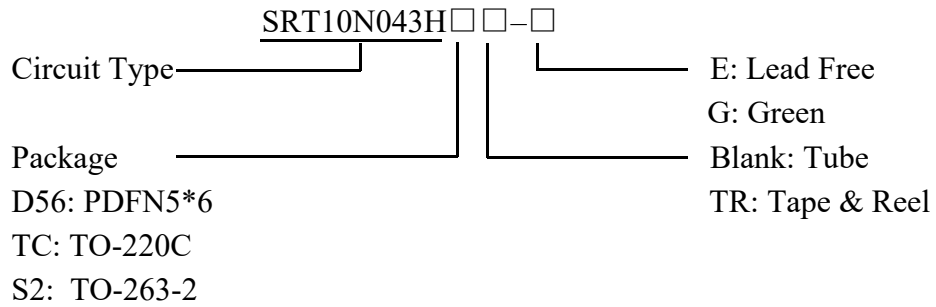


TO-220C, TO-263-2 PDFN5*6
 Figure 1 Symbol of SRT10N043H

Package Type



TO-220C PDFN5*6 TO-263-2
 Figure 2 Package Type of SRT10N043H

Ordering Information


Package	Part Number	Marking ID	Packing Type
PDFN5*6	SRT10N043HD56TR-G	SRT10N043HD56G	Tape & Reel
TO-220C	SRT10N043HTC-E	SRT10N043HTCE	Tube
TO-263-2	SRT10N043HS2TR-E	SRT10N043HS2E	Tape & Reel

Absolute Maximum Ratings

Parameter		Symbol	Rating	Unit	
Drain-Source Voltage		V_{DSS}	100	V	
Gate-Source Voltage		V_{GSS}	±20	V	
Continuous Drain Current	$T_C=25^{\circ}\text{C}$	I_D	PDFN5*6	125	A
			TO-220C	125	
			TO-263-2	125	
	$T_C=100^{\circ}\text{C}$		PDFN5*6	77	
			TO-220C	79	
			TO-263-2	81	
Pulsed Drain Current (Note 2)		I_{DM}	PDFN5*6	500	A
			TO-220C	500	
			TO-263-2	500	
Max Power Dissipation		P_D	119	W	
Avalanche Destructive Energy, Single Pulse (Note 4)		E_{AS_Limit}	625	mJ	
Avalanche Energy, Single Pulse (Note 3)		E_{AS}	110	mJ	
Avalanche Energy, Repetitive (Note 2)		E_{AR}	0.2	mJ	
Avalanche Current, Repetitive (Note 2)		I_{AR}	40.0	A	
Continuous Diode Forward Current		I_S	100	A	
Diode Pulse Current		$I_{S,PULSE}$	300	A	
Operating Junction Temperature		T_J	150	°C	
Storage Temperature		T_{STG}	-55 to 150	°C	
Lead Temperature (Soldering, 10 sec)		T_{LEAD}	260	°C	

Note:

1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating: Pulse width limited by maximum junction temperature
3. $I_{AS}=21.0\text{A}$, $V_{DD}=50\text{V}$, $R_G=25\Omega$, Starting $T_J=25^{\circ}\text{C}$
4. $I_{AS_Limit}=50\text{A}$, $V_{DD}=50\text{V}$, $R_G=25\Omega$, Starting $T_J=25^{\circ}\text{C}$

Thermal Resistance

Parameter		Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	PDFN5*6	R_{thJC}			1.05	°C/W
	TO-220C				0.94	
	TO-263-2				0.94	
Thermal Resistance, Junction-to-Ambient	PDFN5*6	R_{thJA}			50	
	TO-220C				60	
	TO-263-2				60	

Electrical Characteristics
 $T_J = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	100			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=100V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	Forward	$I_{GSSF}, V_{GS}=20V, V_{DS}=0V$			100	nA
	Reverse	$I_{GSSR}, V_{GS}=-20V, V_{DS}=0V$			-100	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=0.25mA$	2.0	3.0	4.0	V
Static Drain-Source On-Resistance	PDFN5*6	$R_{DS(ON)}, V_{GS}=10V, I_D=20A$		3.7	4.3	mΩ
	TO-220C			4.1	4.5	
	TO-263-2			3.9	4.3	
Gate Resistance	R_G	$f=1MHz, \text{Open Drain}$		1.0		Ω
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=50V, V_{GS}=0V, f=1MHz$		3.9		nF
Output Capacitance	C_{OSS}			1.3		nF
Reverse Transfer Capacitance	C_{RSS}			24		pF
Effective output capacitance, energy related NOTE5	$C_{O(er)}$	$V_{GS}=0V, V_{DS}=0\dots 60V$		1.7		nF
Effective output capacitance, time related NOTE6	$C_{O(tr)}$			2.1		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=50V, I_D=20A, R_G=3.0\Omega, V_{GS}=10V$		14		nS
Rise Time	t_r			7		
Turn-off Delay Time	$t_{d(off)}$			32		
Fall Time	t_f			11		
Gate Charge Characteristics						
Gate to Source Charge	Q_{gs}	$V_{DD}=50V, I_D=20A, V_{GS}=0 \text{ to } 10V$		16		nC
Gate to Drain Charge	Q_{gd}			11		
Gate Charge Total	Q_g			57		
Gate Plateau Voltage	$V_{plateau}$			4.2		V
Gate Charge Total, sync FET	Q_g	$V_{DD}=0.1V, V_{GS}=0 \text{ to } 10V$		49		nC
Reverse Diode Characteristics						
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=20A$		0.81	1.0	V
Reverse Recovery Time	t_{rr}	$V_R=50V, I_F=20A, dI_F/dt=100A/\mu s$		50		nS
Reverse Recovery Charge	Q_{rr}			75		nC
Peak Reverse Recovery Current	I_{rrm}			3		A

Note:

- $C_{O(er)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 60V
- $C_{O(tr)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 60V



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